

3-24-03

04-03-2003



To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of conveying party(ies):
 1. Chi Tsung CHIU
 2. Ted WANG
 3. Samuel WU
 4. Jenny CHEN

2. Name and address of receiving party(ies):
 Name: **ADVANCED SEMICONDUCTOR ENGINEERING, INC.**
 Internal Address:
 Street Address: **No. 26, Chin 3rd Road, Nantze Export Processing Zone, Kaoshiung**

11040 U.S. PTO 10/394347



Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

City: **Taiwan** State:
 Zip: Country: **Republic of China**

Execution Date November 7, 2002

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
 If the document is being filed together with a new application, the execution date of the application is: November 7, 2002

A. Patent Application No(s). **filed** **10394347**
 B. Patent No(s). **issued**

Additional numbers attached? Yes No

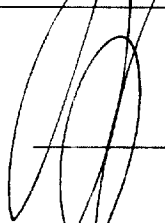
5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: **LOWE HAUPTMAN GILMAN & BERNER**
 Internal Address:
 Street Address: **1700 Diagonal Road, Suite 310**
 City: **Alexandria** State: **VA** Zip: **22314**

6. Total number of applications and patents involved: **one**

7. Total fee (37 CFR 3.41), \$ **40.00**
 Enclosed
 Authorized to be charged to deposit account
 Credit Card payment form enclosed

8. Deposit account number: 07-1337

DO NOT USE THIS SPACE

9. Signature.
 Benjamin J. Hauptman, 29,310
 Name of Person, Registration No.  Signature **March 24, 2003** Date

Total number of pages including cover sheet, attachment, and document: 2

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) Chi Tsung CHIU
- (2) Ted WANG
- (3) Samuel WU
- (4) Jenny CHEN
- (5) _____
- (6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto
Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR PACKAGE AND SUBSTRATE THEREOF

- (a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or
- (b) for which an application for United States Letters Patent was executed on November 7, 2002,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS	DATE SIGNED
1) Signature: <u>Chi Tsung Chiu</u> Name: Chi Tsung CHIU	<u>November 7, 2002</u>
2) Signature: <u>Ted Wang</u> Name: Ted WANG	<u>November 7, 2002</u>
3) Signature: <u>Samuel Wu</u> Name: Samuel WU	<u>November 7, 2002</u>
4) Signature: <u>Jenny Chen</u> Name: Jenny CHEN	<u>November 7, 2002</u>
5) Signature: _____ Name: _____	_____
6) Signature: _____ Name: _____	_____